

ABSTRACT

A semiconductor package includes a first semiconductor chip on a first substrate, a first mold layer provided on the first substrate to cover a side surface of the first semiconductor chip, a solder structure provided on the first substrate, and a second substrate provided on the solder structure. A guide receptacle is formed at one of a top surface of the first mold layer and a bottom surface of the second substrate, a first alignment protrusion is formed at the other of the top surface of the first mold layer and the bottom surface of the second substrate, and at least a portion of the first alignment protrusion is provided in the guide receptacle.

FIG. 1